ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan-Ameri	nockburn, Illinois, A	Il rights reserved unontions.	der both Ievel	documen l parts, the	nt is a declaration e declaration end	n of the substance compasses all low	es within the manufactur wer level materials for wl	er listed	item. Note: if nanufacturer	the item is an as has engineering	sembly with lower responsibility.	
			Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					on			
Supplier Information												
Company name* Company unique ID				Unique ID Authority			Response Date*					
onsemi									2024-04-25			
Contact Name	ne Title - Contact			Phone - Contact*				Email - Contact*				
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative				Phone - Representative*			Email - Representative*					
Product-Env-Stewards Product Enviro Com			Compliance N		NA			Product-Env-Stewards@onsemi.com				
Requester Item Number M:	fr Item Number	Mfr Item Name		I	Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
SL	JRS8340T3G	58340T3G 3A 400V ULTRAFAST		2	2024-04-25		VN5		228.02	mg	Each	
Manufacturing Proccess Information						·				·		
Terminal Plating / Grid Array Material	Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-0		STD-020 MSL Rati	ing	Peak Proces	s Body Tempera	ture Max Time at Peak	Tempera	ture Numbe	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy 1					260	С	30	seco	nds 3			
Comments												
evel 1 - maximum time at peak temperature dur	ing soldering is 10-3	0 seconds										
or more information regarding material compo	sition please refer to	page 3										

RoHS Material Composition Declar	ation			Declaration Type *	Detailed						
Directive 2015/863/EU amending Rol Directive 2011/65/EU											
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part,the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of						
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the						
Supplier Digital Signature	Rastislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).								
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.34	mg	Supplier	Silicon (Si)	7440-21-3		1.3266	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0134	mg
Die Attach Solder	5.17	mg	Supplier	Silver (Ag)	7440-22-4		0.1293	mg
			А	Lead (Pb)	7439-92-1	7a	4.7822	mg
			Supplier	Tin (Sn)	7440-31-5		0.2585	mg
Lead Frame	92.28	mg	Supplier	Zinc (Zn)	7440-66-6		0.0923	mg
			Supplier	Iron (Fe)	7439-89-6		2.2147	mg
			Supplier	Copper (Cu)	7440-50-8		89.973	mg
Mold Compound-Black	126.72	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		12.672	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6336	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		18.3744	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		82.368	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		12.672	mg
Plating	2.51	mg	Supplier	Tin (Sn)	7440-31-5		2.51	mg